



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

EXAMINER: N. PAREKH

Art Unit 2811

APPLICANT: PETER ELENUS, ET AL.

SERIAL NO.: 09/575,298

FILED: May 19, 2000

FOR: "SOLDER BAR FOR HIGH POWER
FLIP CHIPS"

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Marvin A. Glazer
Marvin A. Glazer

October 24, 2002
Date

AMENDMENT

BOX CPA
Honorable Commissioner for Patents
Washington, D.C. 20231

Sir:

IN THE CLAIMS:

Please amend claim 16 as follows:

16. A reflowable solder bar formed upon an upper surface of a first substrate, the first substrate having a first electrical contact, said reflowable solder bar being adapted to join the first electrical contact to a second electrical contact on a second substrate, said reflowable solder bar comprising in combination:

a. a first generally circular solder pad formed upon the upper surface of the first substrate, the first generally circular solder pad having a center, and having a first predetermined diameter D;

Sub
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